

JUL 03 2006

IN THE SPECIFICATION:

On page 9 of the specification, please amend the description of Fig. 1, as follows:

~~FIG. 1~~ FIGS. 1A-1D ~~is an illustration~~ are illustrations showing a first embodiment of the present invention;

On page 11 please amend the paragraph beginning on line 8 and ending on line 14 as follows:

~~Fig. 1 illustrates~~ FIGS. 1A-1D illustrate an ILS with an embodiment of the present invention. A via is created in the ILS through the stainless steel layer 212 at 204, the polyimide layer 210 at 202, and the copper layer 208 at 200 that exposes the arm surface. A drop of conductive adhesive is placed in the via to connect the stainless steel layer through the polyimide layer to the copper layer and the arm surface.

IN THE CLAIMS:

Please amend the claims as follows:

1. (Currently amended) A method of creating a conductive path between two or more conductive layers, wherein the conductive layers are separated by one or more dielectric layers, the method comprising:
applying a conductive material to exposed portions of at least two conductive layers, the conductive material creating an electrical coupling between the conductive layers; and
grounding at least one of the conductive layers to a controlled ground potential;
wherein the portions of the conductive layers are exposed by recessing an edge of at least one of the conductive layers and any dielectric layers positioned between the conductive layers to form stepped back edges on